

✓  
change "become" to -- became --; line 13, insert "the" before "thin"; line 14, change "are" to -- were --; line 18, delete "very".

IN THE CLAIMS:

Please cancel claims 1 to 11, and 15.

B2  
Sub J2  
001550-0251560  
12. (amended) A chemical-mechanical polishing process for planarizing [at least] one or more [of thin] films formed on a substrate, wherein the chemical-mechanical polishing is performed using a slurry containing abrasive particles [mainly made of] containing boehmite.

13. (unchanged) A chemical-mechanical polishing process according to claim 12, wherein the particles of boehmite are formed by dipping of particles of Al in hot water.

14. (unchanged) A chemical-mechanical polishing process according to claim 13, wherein said hot water is added with sodium aluminate.

B3  
Sub J2  
16. (amended) A chemical-mechanical polishing process for planarizing [at least] one or more [of thin] films formed on a substrate, wherein said thin films are subjected to chemical-mechanical polishing using a slurry containing

by  
Sub 1  
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~~abrasive particles [mainly made of] containing boehmite, and the residual slurry and contamination are removed by spin cleaning.~~

17. (amended) A chemical-mechanical polishing process according to claim 16, wherein said spin cleaning is performed using chemicals comprising [NH<sub>4</sub>-H<sub>2</sub>O-H<sub>2</sub>O and dilute] a solution containing NH<sub>4</sub>, H<sub>2</sub>O<sub>2</sub>, and H<sub>2</sub>O, followed by a hydrofluoric acid solution.

18. (unchanged) A chemical-mechanical polishing process according to claim 17, wherein after spin cleaning using said chemicals, said substrate is rinsed with pure water.

19. (unchanged) A chemical-mechanical polishing process according to claim 16, wherein the abrasive particles of boehmite are formed by dipping of particles of Al in a hot water.

20. (unchanged) A chemical-mechanical polishing process according to claim 19, wherein said hot water is added with sodium aluminate.

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